NPN 100mA 50V Digital Transistor (Bias Resistor Built-in Transistor)

Parameter	Value
V _{CEO}	50V
I _C	100mA
R ₁	10kΩ

Features

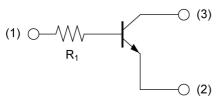
- 1) Built-In Biasing Resistor
- 2) Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 4) Complementary PNP Types: DTA114T series

Application

INVERTER, INTERFACE, DRIVER

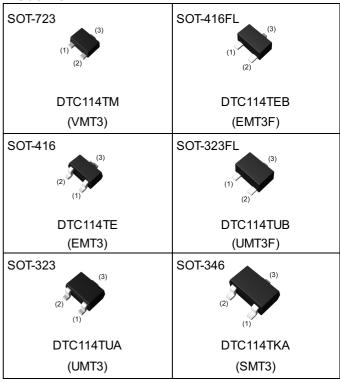
Inner circuit

DTC114TM/ DTC114TEB/ DTC114TUB

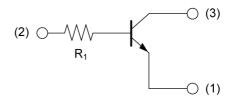


- (1) BASE
- (2) EMITTER
- (3) COLLECTOR

Outline



DTC114TE/ DTC114TUA/ DTC114TKA



- (1) EMITTER
- (2) BASE
- (3) COLLECTOR

Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
DTC114TM	SOT-723	1212	T2L	180	8	8000	04
DTC114TEB	SOT-416FL	1616	TL	180	8	3000	04
DTC114TE	SOT-416	1616	TL	180	8	3000	04
DTC114TUB	SOT-323FL	2021	TL	180	8	3000	04
DTC114TUA	SOT-323	2021	T106	180	8	3000	04
DTC114TKA	SOT-346	2928	T146	180	8	3000	04

● Absolute maximum ratings (T_a = 25°C)

Pa	arameter	Symbol	Values	Unit
Collector-base voltage			50	V
Collector-emitter voltage	Collector-emitter voltage			V
Emitter-base voltage			5	V
Collector current	nt I _C 100			mA
	DTC114TM		150	mW
	DTC114TEB		150	
Davis a disaination	DTC114TE	P _D *1	150	
Power dissipation	DTC114TUB	P_{D} .	200	
	DTC114TUA		200	
	DTC114TKA		200	
Junction temperature			150	°C
Range of storage temperate	ture	T _{stg}	-55 to +150	°C

• Electrical characteristics $(T_a = 25^{\circ}C)$

Davanastan	Symbol Conditions —		Values			Linit
Parameter			Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV _{CBO}	I _C = 50μA	50	-	-	V
Collector-emitter breakdown voltage	BV _{CEO}	I _C = 1mA	50	-	-	V
Emitter-base breakdown voltage	BV _{EBO}	I _E = 50μA	5	-	-	V
Collector cut-off current	I _{CBO}	V _{CB} = 50V	-	1	500	nA
Emitter cut-off current	I _{EBO}	V _{EB} = 4V	-	-	500	nA
Collector-emitter saturation voltage	V _{CE(sat)}	I _C = 10mA, I _B = 1mA	-	-	300	mV
DC current gain	h _{FE}	V _{CE} = 5V, I _C = 1mA	100	250	600	-
Input resistance	R ₁	-	7	10	13	kΩ
Transition frequency	f _T *2	V _{CE} = 10V, I _E = -5mA, f = 100MHz	-	250	-	MHz

^{*1} Each terminal mounted on a reference land.

^{*2} Characteristics of built-in transistor

● Electrical characteristic curves(Ta=25°C)

Fig.1 Grounded emitter propagation characteristics

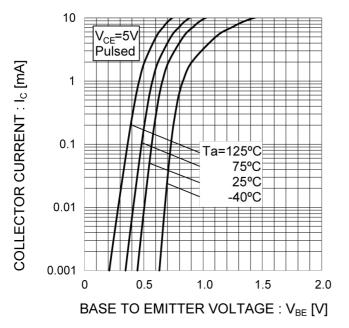
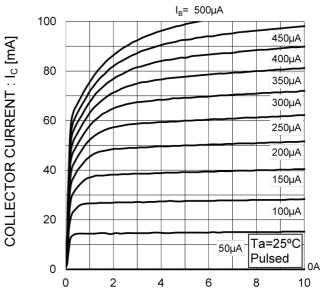


Fig.2 Typical Output Characteristics



COLLECTOR TO EMITTER VOLTAGE : $V_{CE}\left[V\right]$

Fig.3 DC Current Gain vs. Collector

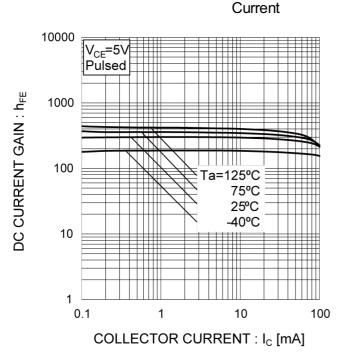
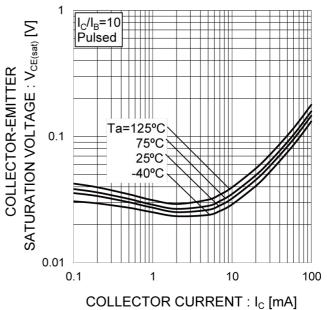
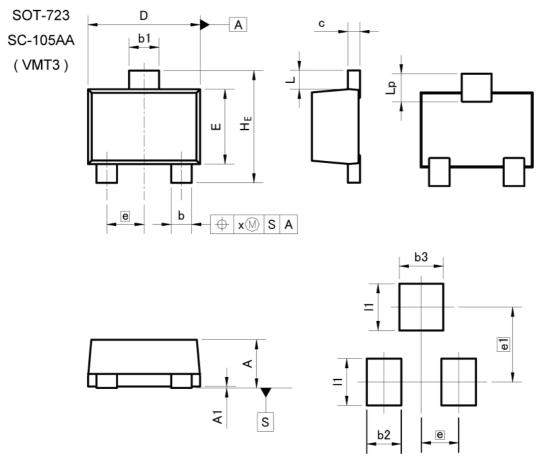


Fig.4 Collector-Emitter Saturation
Voltage vs. Collector Current





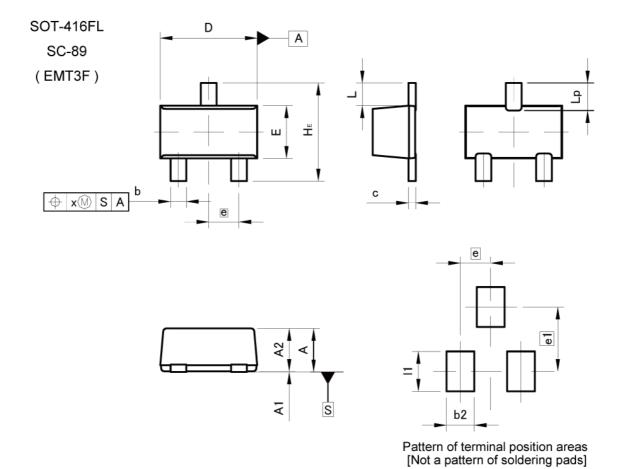
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	MILIMETERS INCH		HES
DIM	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
С	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
е	0.4	40	0.02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
х	_	0.10	_	0.004

DIM	MILIM	ETERS	INCHES	
	MIN	MAX	MIN	MAX
b2	-	0.37	_	0.015
b3	_	0.47	7-	0.019
e1	0.80		0.0	31
11	=	0.50		0.020

Dimension in mm/inches



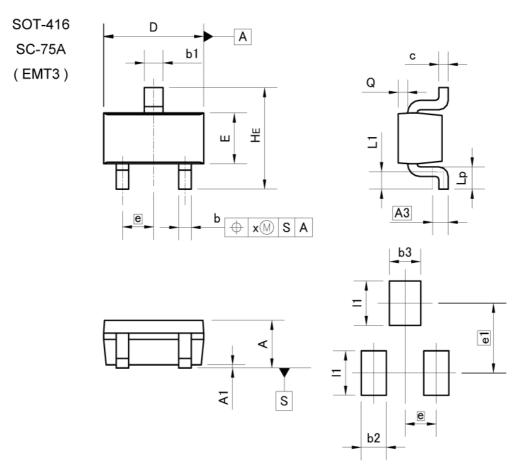


DIM	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.65	0.85	0.026	0.033
A1	0.00	0.10	0.000	0.004
A2	0.60	0.80	0.024	0.031
b	0.21	0.36	0.008	0.014
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	0.76	0.96	0.030	0.038
е	0.	50	0.0	20
HE	1.50	1.70	0.059	0.067
L	0.37		0.0	15
Lp	0.35	0.55	0.014	0.022
Х	<u> </u>	0.10	-	0.004

DIM	MILIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
b2	-	0.46	-	0.018	
e1	-	1.05	-	0.041	
11	-	0.65	-	0.026	

Dimension in mm/inches





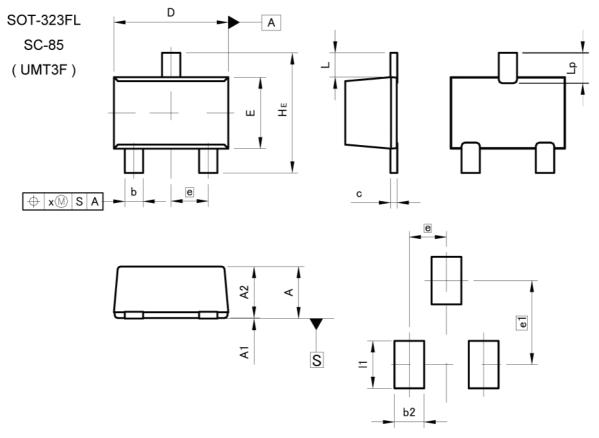
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.60	0.80	0.024	0.031
A1	0.00	0.10	0.000	0.004
A3	0.:	25	0.0	10
b	0.15	0.30	0.006	0.012
b1	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
е	0.	50	0.0	20
HE	1.40	1.80	0.055	0.071
L1	0.10	-	0.004	-
Lp	0.15		0.006	<i>∞</i> =
Q	0.05	0.25	0.002	0.010
х	-	0.10	,-	0.004

DIM	MILIM	ETERS	INCHES	
DIW	MIN	MAX	MIN	MAX
b2	J	0.40	-	0.016
b3	I	0.50	-	0.020
e1	1.10		0.0	43
l1		0.70		0.028

Dimension in mm/inches





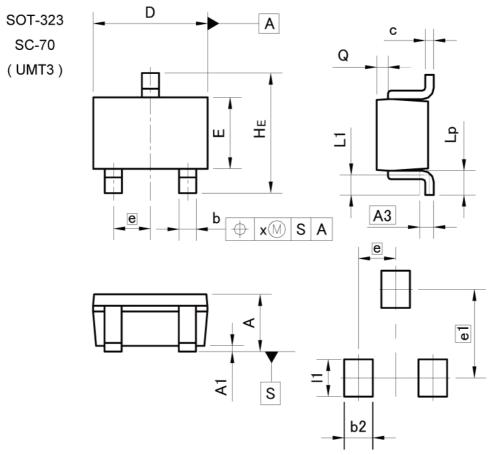
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIN	MIN	MAX	MIN	MAX	
Α	0.85	1.05	0.033	0.041	
A1	0.00	0.10	0.000	0.004	
A2	0.80	1.00	0.031	0.039	
b	0.27	0.42	0.011	0.017	
С	0.08	0.18	0.003	0.007	
D	1.90	2.10	0.075	0.083	
E	1.15	1.35	0.045	0.053	
е	0.0	65	0.026		
HE	2.00	2.20	0.079	0.087	
L	0.425		0.0	17	
Lp	0.43	0.63	0.017	0.025	
х	_	0.10	-	0.004	

	DIM	MILIMETERS		INCHES	
L		MIN	MAX	MIN	MAX
	b2	_	0.52	-	0.020
	e1	1.47		0.0	58
	I1	- 0.83		ı	0.033

Dimension in mm/inches





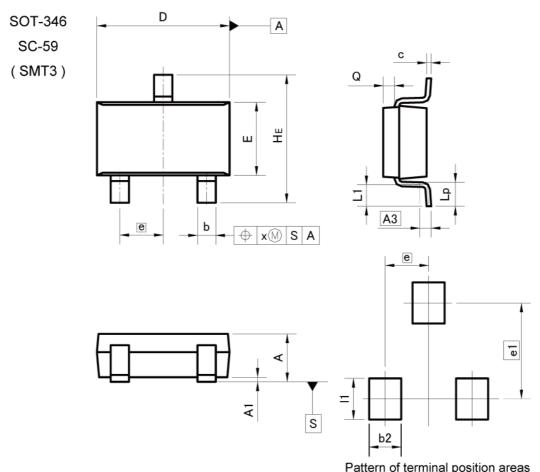
Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.25	0.40	0.010	0.016
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L1	0.10	0.40	0.004	0.016
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
х	_	0.10	-	0.004

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	_	0.50	_	0.020
e1	1.55		0.061	
- 11	-	0.65	-	0.026

Dimension in mm/inches





Pattern of terminal position areas
[Not a pattern of soldering pads]

MILIMETERS INCHES

MIN MAY MIN MAY

DIM	MILIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.25		0.010	
b	0.35	0.50	0.014	0.020
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x	-	0.10	6 -7	0.004
У	-,	0.10	0 	0.004

DIM	MILIMETERS		INCHES		
	DIM	MIN	MAX	MIN	MAX
	b2	-	0.60	-	0.024
	e1	2.10		0.083	
	11	-2	0.90	-	0.035

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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